

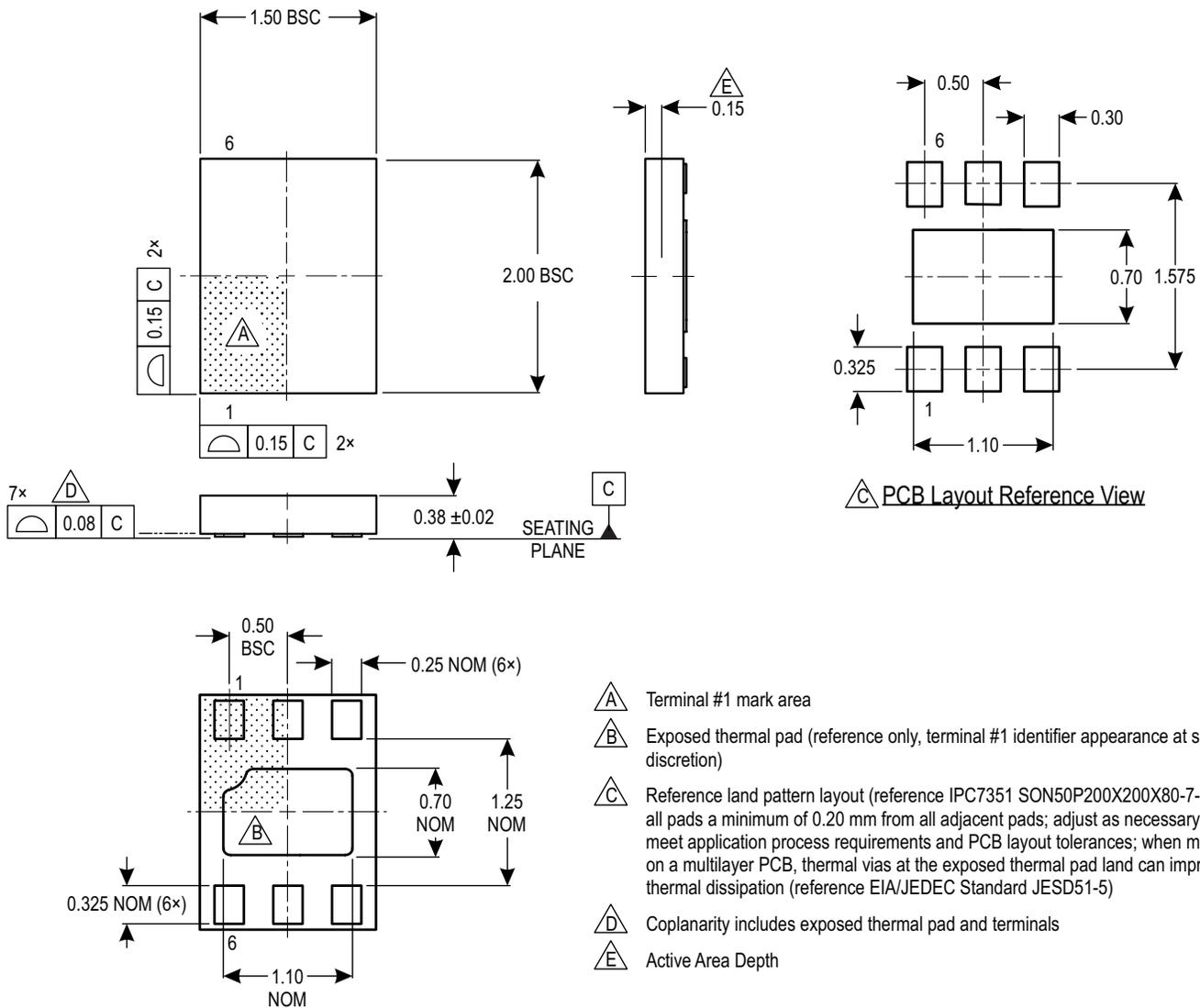
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Reference DWG-0000368)

Dimensions in millimeters

NOT TO SCALE

Exact case and lead configuration at supplier discretion within limits shown



-  Terminal #1 mark area
-  Exposed thermal pad (reference only, terminal #1 identifier appearance at supplier discretion)
-  Reference land pattern layout (reference IPC7351 SON50P200X200X80-7-M); all pads a minimum of 0.20 mm from all adjacent pads; adjust as necessary to meet application process requirements and PCB layout tolerances; when mounting on a multilayer PCB, thermal vias at the exposed thermal pad land can improve thermal dissipation (reference EIA/JEDEC Standard JESD51-5)
-  Coplanarity includes exposed thermal pad and terminals
-  Active Area Depth

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